

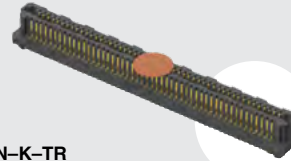


LSEM-150-03.0-F-DV-A-N-K-TR

LSEM-120-06.0-F-DV-A-N-K-TR



LSEM-120-01-L-DH-A-N-K-TR



LSEM SERIES

(0.80 mm) .0315"

HIGH-SPEED HERMAPHRODITIC STRIP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LSEM

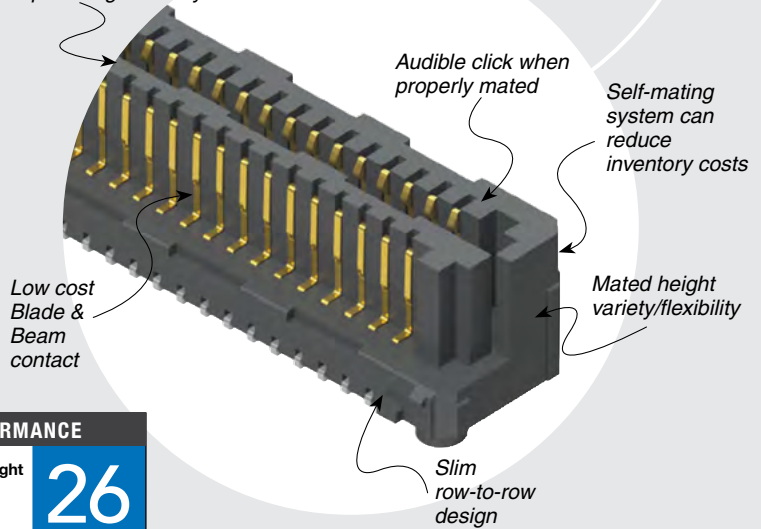
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating:
1.8 A per pin (2 adjacent pins powered)
Operating Temp Range:
-55 °C to +125 °C
RoHS Compliant:
Yes

Mates with:
LSEM

RUGGEDIZED
BY SAMTEC

- High retention contacts
- Audible click when mated
- Shrouded

High-speed/High-density



PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

HIGH-SPEED CHANNEL PERFORMANCE

LSEM-DV/LSEM-DV @ 10 mm Mated Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

26
Gbps

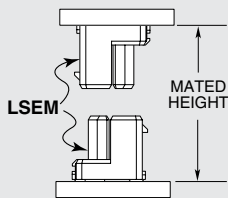
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



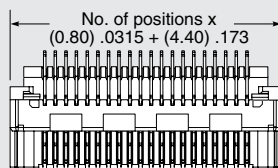
LSEM	1	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	TAIL OPTION	A	N	K	TR
		20, 30, 40, 50	Specify LEAD STYLE from chart	-F = Gold flash on contact, Matte Tin on tail -L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail	-DV = Vertical -DH = Right-angle (Lead style -01 only)			-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad	-TR = Tape & Reel

APPLICATION

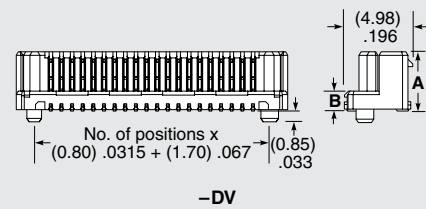
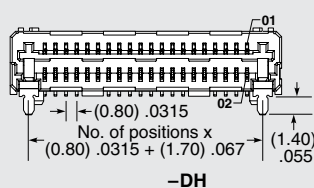
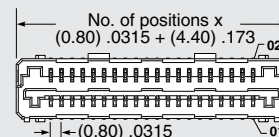


LEAD STYLE	MATED HEIGHT*
-03.0 & -03.0	(6.00) .236
-03.0 & -04.0	(7.00) .276
-04.0 & -04.0	(8.00) .315
-03.0 & -06.0	(9.00) .354
-04.0 & -06.0	(10.00) .394
-06.0 & -06.0	(12.00) .472

*Processing conditions will affect mated height.



LEAD STYLE	A	B
-01 (-DH only)	NA	NA
-03.0	(4.45) .175	(1.50) .059
-04.0	(5.45) .215	(2.50) .098
-06.0	(7.45) .293	(4.50) .177



Note: Some lengths, styles and options are non-standard, non-returnable.